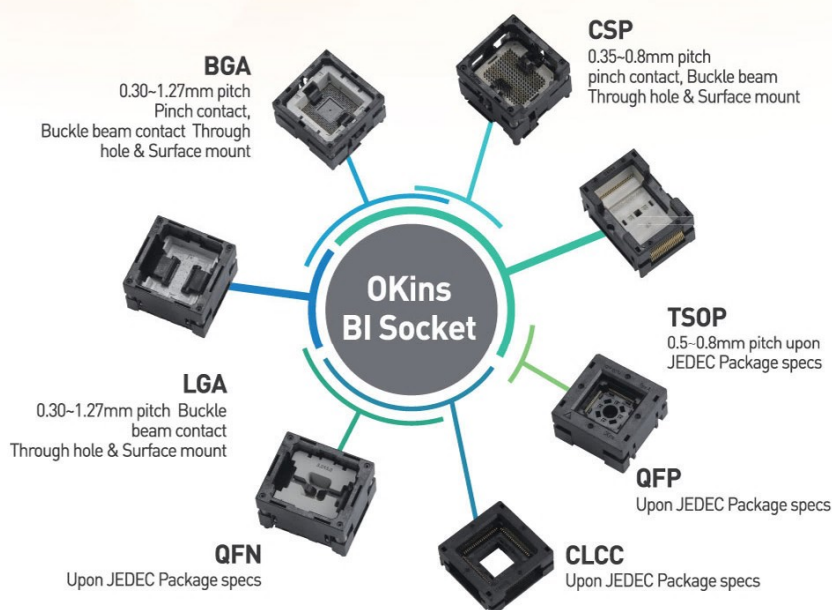


Burn-in Socket

- 3-points or 4-points crown buckle beam contact to package ball
- More stable ball contact for better Contact resistance
- Applicable for all normal contact and fine pitch of LPDDR



Design Features

- Design Features
- Open top auto-load actuation
- 3-points or 4-points crown buckle beam contact
- Contact pitch possible for 0.3 mm ~1.0P

Socket Specifications

- Socket body : PEI or equivalent
- Contact : BeCu, PdCo plate
- Contact Force : 11 gf
- Contact Resistance : $\leq 50m\Omega$
- Insertion : 10,000 cycles and over

LPDDR Burn-in Socket List

PKG Application	PITCH	PKG	PKG SIZE	Contact	P/N	Socket Size
4G LPDDR2 LPDDR3	0.4	216FBGA	12*12	Bow	B1216A-A2C46	23*28
	0.65*0.8	178FBGA	11*11.5	Dual	7F92-178V-1014	22*28
	0.35	426FBGA	13.5*14.5	Bow	B6426G-A1H94	28*26
	0.35*0.45	345FBGA	13.5*13.5	Bow	B6345G-A1J65	26*28
	0.4	361FBGA	13*13	Bow	B6361A-A1H50	28*26
	0.4	256FBGA	14*14	Bow	B6256A-B1K46	28*26
	0.4	261FBGA	10*10	Bow	B6261A-A1K13	28*26
	0.5	216FBGA	15*15	Dual	7H92-216B-1001	26*26
	0.5	253FBGA	11*11.5	Bow	B3253B-A1G57	26*26
	0.4*0.6	396LPDDR3 6G	15*15	Bow	B6396A-A1K33	28*26
LPDDR4	0.35	296FBGA 8G	14*14	Bow	B6296G-A1G11	26*28
	0.35	456FBGA 8G	14*15.5	Bow	B6456G-A1H23	28*26
	0.3	386FBGA	14.20*15.51	Bow	B9386H-A1N05	26*29
	0.35	450FBGA	14.46*14.80	Bow	B6450G-A1L22	28*26
DDR4	0.5	366FBGA	15*15	Bow	B6366B-A1K40	26*28
DDR4	0.8	78/96FBGA DDR4	11*11	Dual	7A95-078D-1028	22*27.4
CI MCP	0.5	221FBGA	11.5*13	Bow	B3221B-A1K35	26*26
	0.5	162FBGA	11.5*13	Bow	B3162B-A1K36	26*26
eMMC	0.5	153FBGA	11.5*13	Dual	7H92-153B-959	26*26
	0.5	162FBGA	11.5*13	Dual	7H92-162B-1132	26*26
GRAPHIC DDR5	0.8	170FBGA	12*14	Dual	7A95-170D-985	22*27.4
NAND FLASH	0.8	316NAND FLASH	14*18	Dual	7F95-316D-986	22*28
	1	132FBGA	12*18	Pinch	7C52-132B-988	22*26
	1	108NAND FLASH	11.2*14	Pinch	7C52-180B-459	22*26
	1	132NAND FLASH	11.2*14	Pinch	7C52-180B-459	22*26